TWSE: 6515

穎崴科技股份有限公司

WinWay Technology

BofA 2024 APAC TMT Conference

2024/03/19

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Company Information

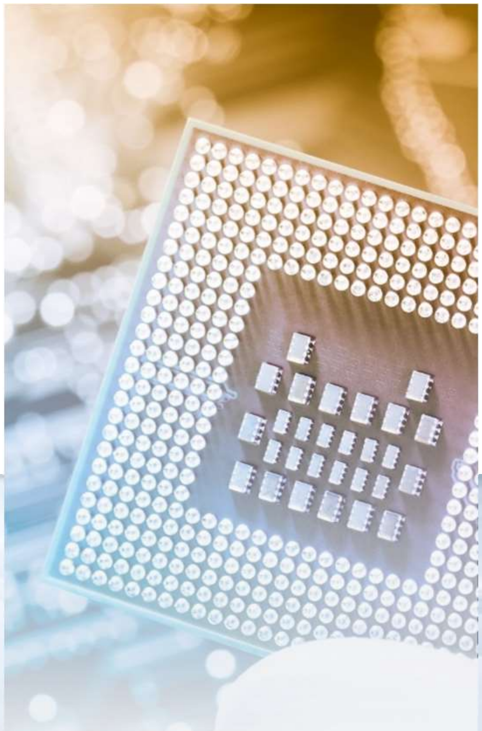
Founded	**2001/04 /10**
Business Operation	**Design, manufacture, sale and service of test interface products**
Chairman & CEO	**Mark Wang**
Capital Stock	**NTD 347,796,200**
Employees	**879**
Registered Address	**No.68, Chuangyi S. Rd, Nanzi Dist. Kaohsiung City 81156, Taiwan**

Agenda


Global Presence


Industry Trend


Financial Performance


R&D Innovation

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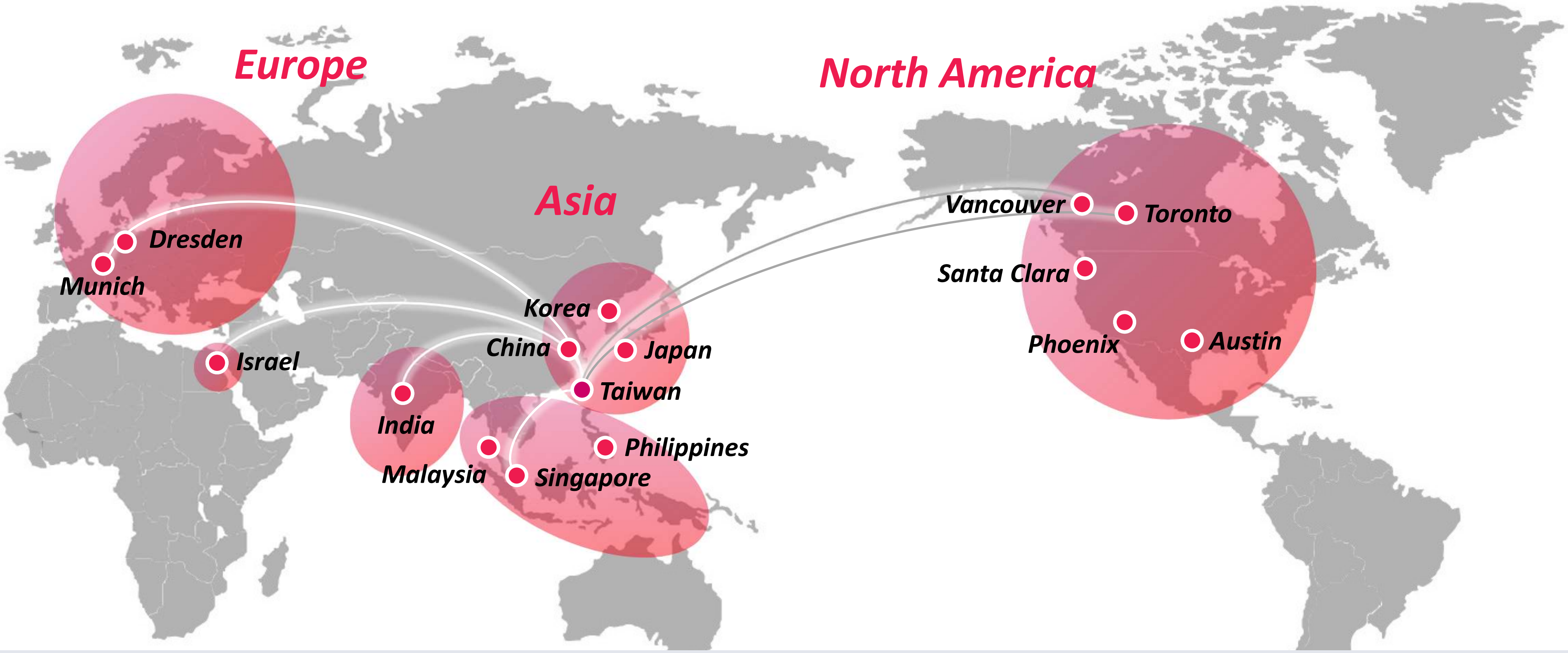
01

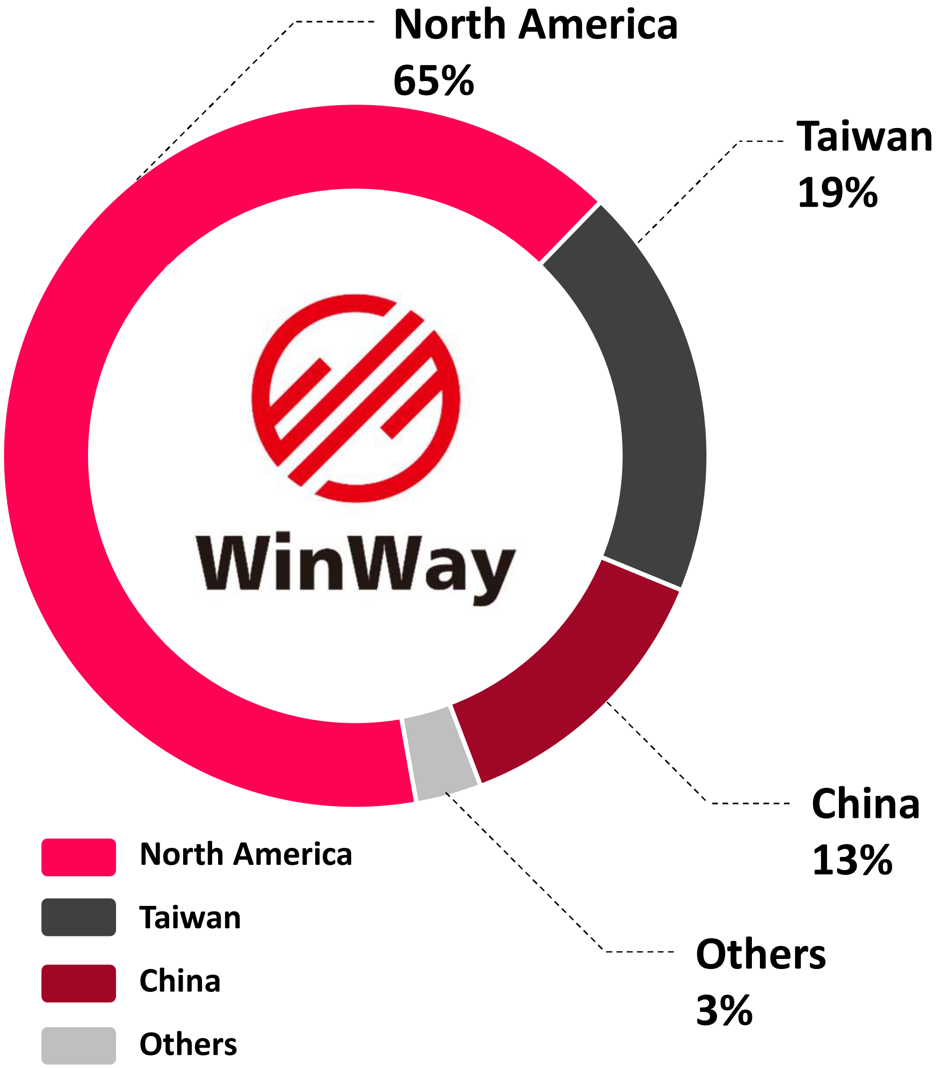
Global Presence

Global Service & Support Network



- Kaohsiung Spring Probe Plant
- Kaohsiung Plant
- Hsinchu Plant
- Suzhou Plant

Worldwide Customer



82%

Top10 IC Design

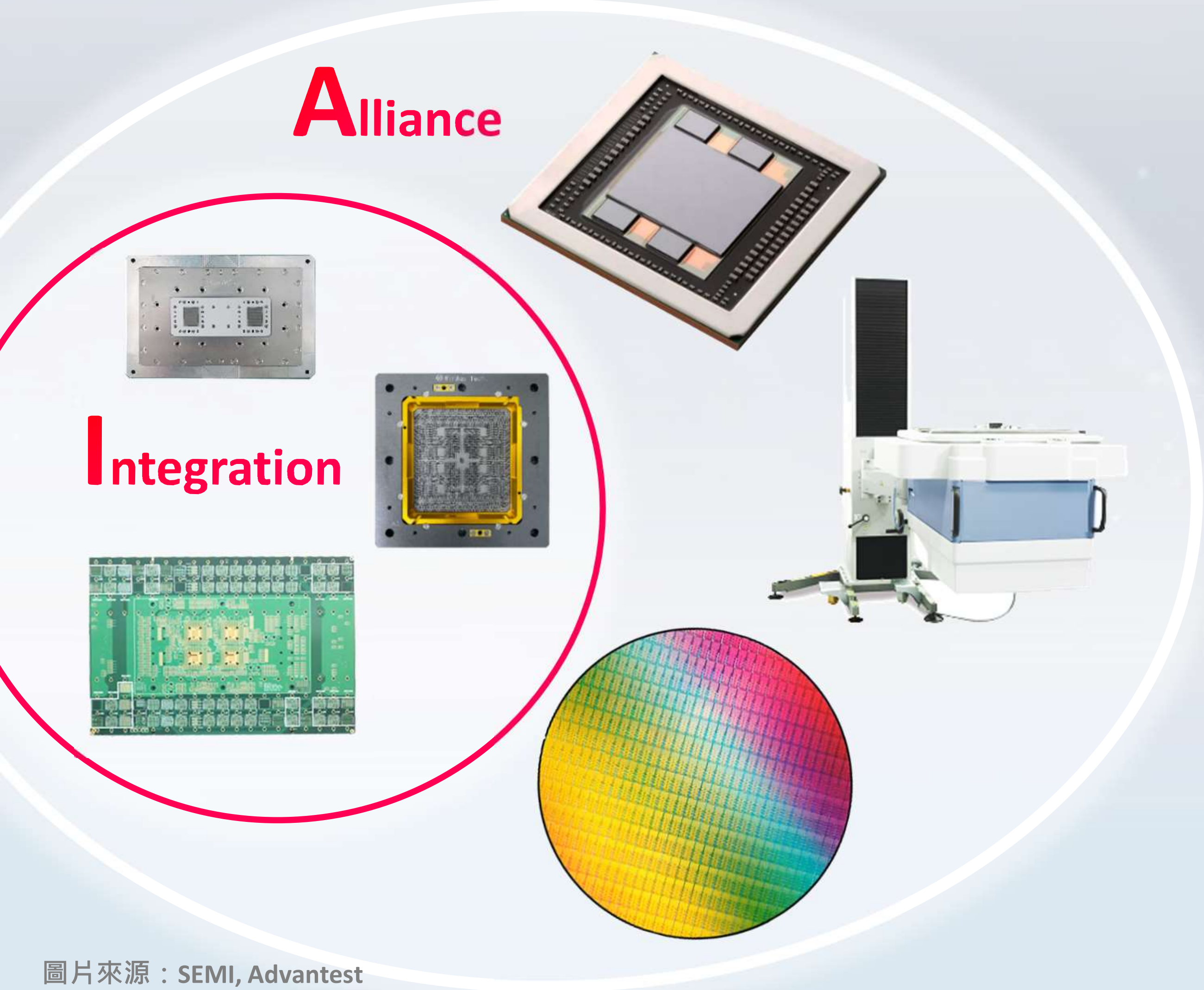
200+

Active Customers

02

Industry Trend

New Opportunities in the Semiconductor Industry



Alliance

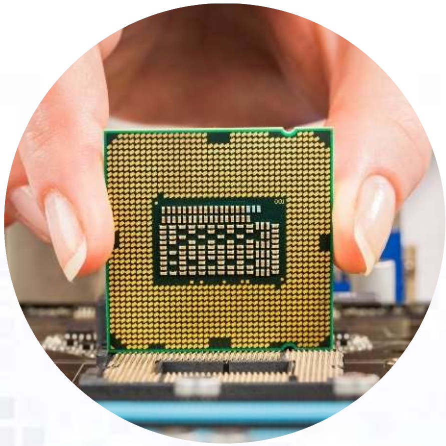
Integration

Artificial Intelligence

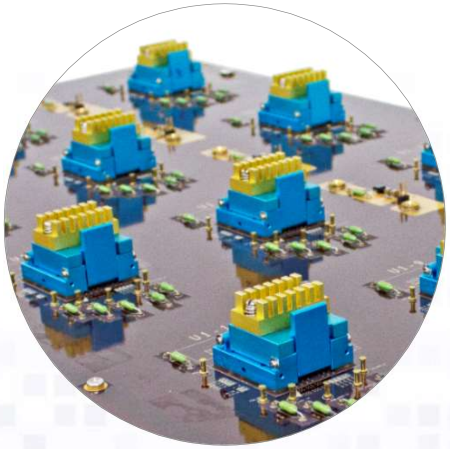
CPU、GPU、HPC

圖片來源：SEMI, Advantest

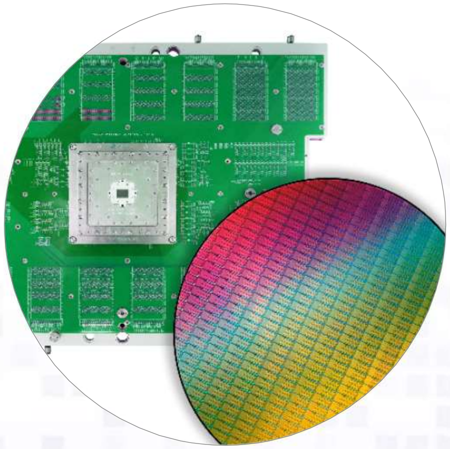
Test Interface Total Solution



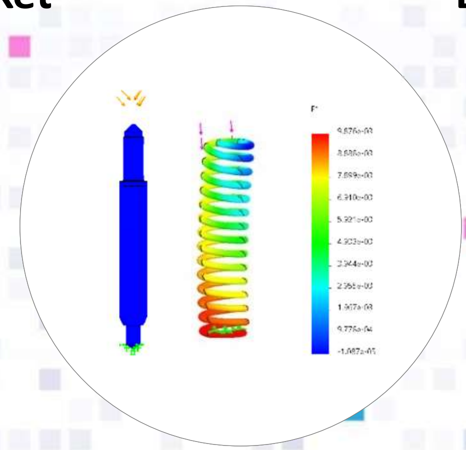
Coaxial Test Socket



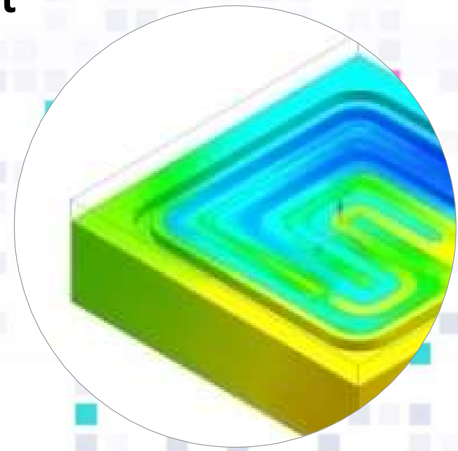
Burn-in Socket



Vertical Probe Card

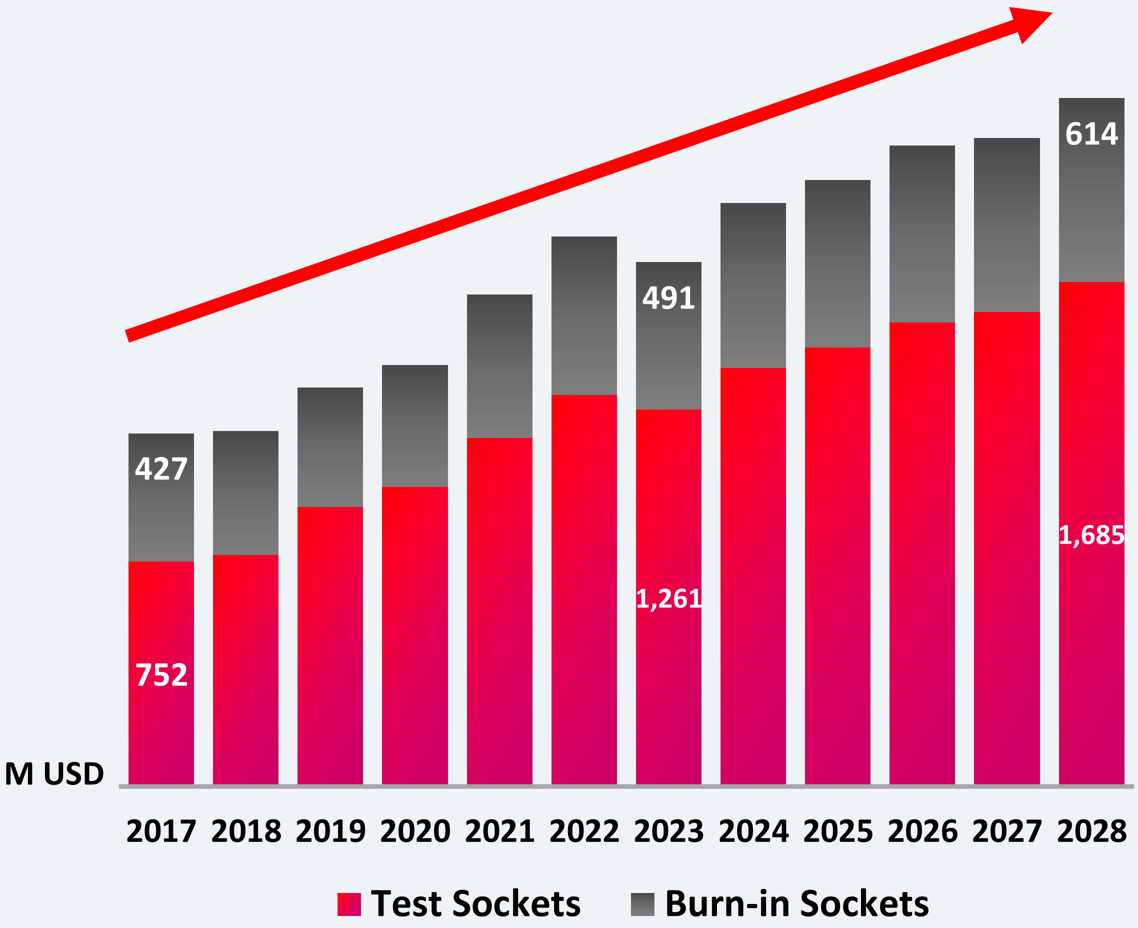


Spring Probe



Thermal Control System

Greater Need for System Level Test



SLT

2022-2027 CAGR

13.2%

Greater than industry growth

Burn-in

2022-2027 CAGR

6.0%

Mission Critical Systems

SOURCE: Yole, WinWay 2023

Leadership in Semiconductor Test Interface

SOURCE: Yole Group 2024

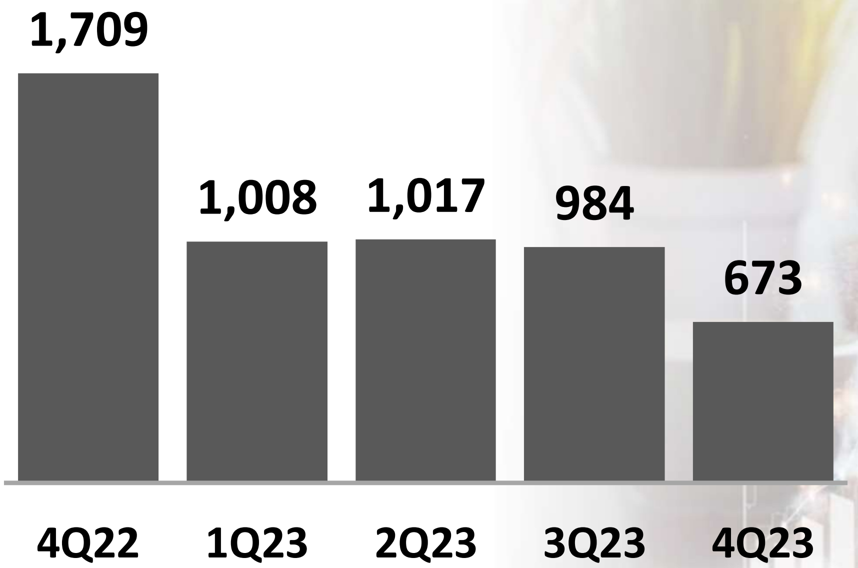
Test and Burn-in Socket Ranking	Test Socket Ranking	Probe Card Ranking
5	3	-

03 Financial Performance

Revenue Trend

QUARTERLY REVENUE

(NTD MILLION)

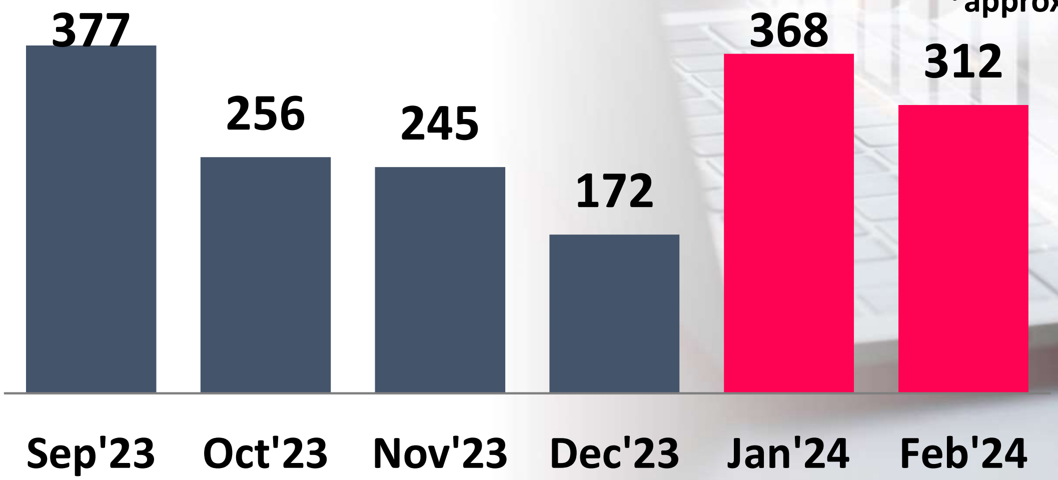


3.7B

2023 Full Year
*approx. USD 119M

MONTHLY REVENUE

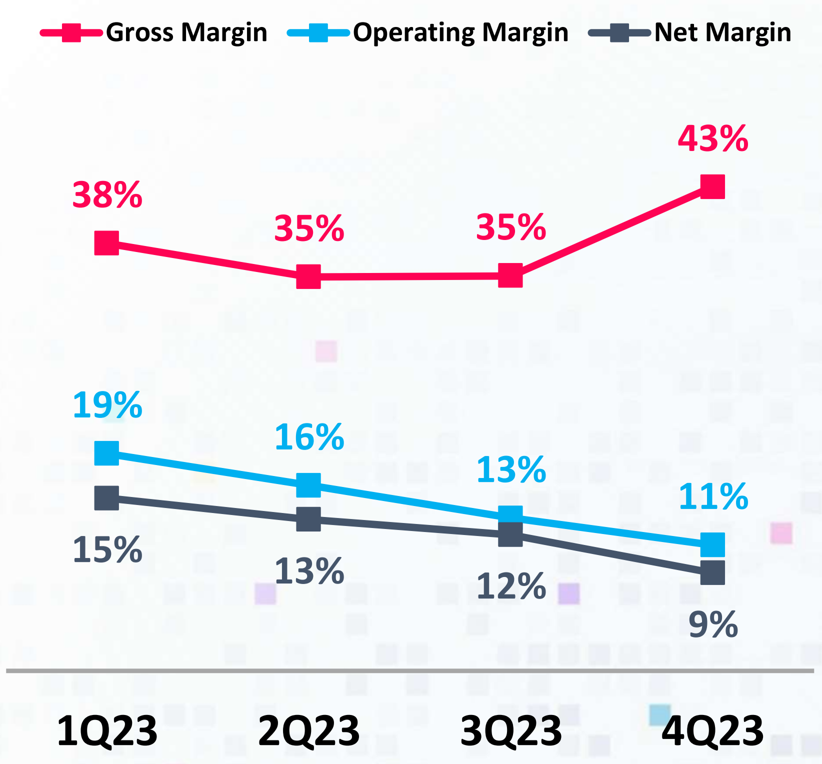
(NTD MILLION)



Profitability Trend

2023 EPS
(NT$) **13.52**

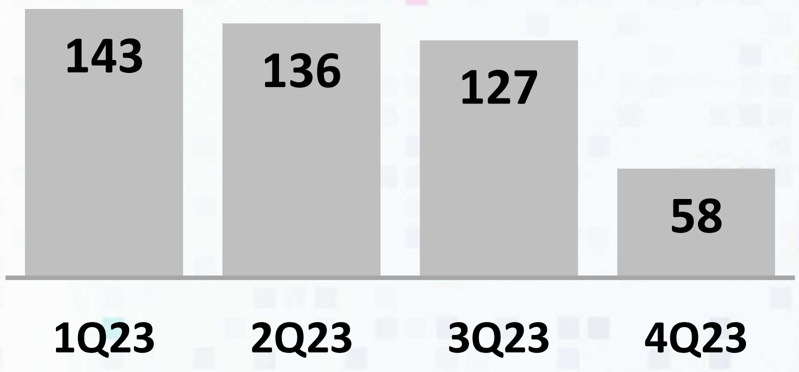
Dividend
11.0



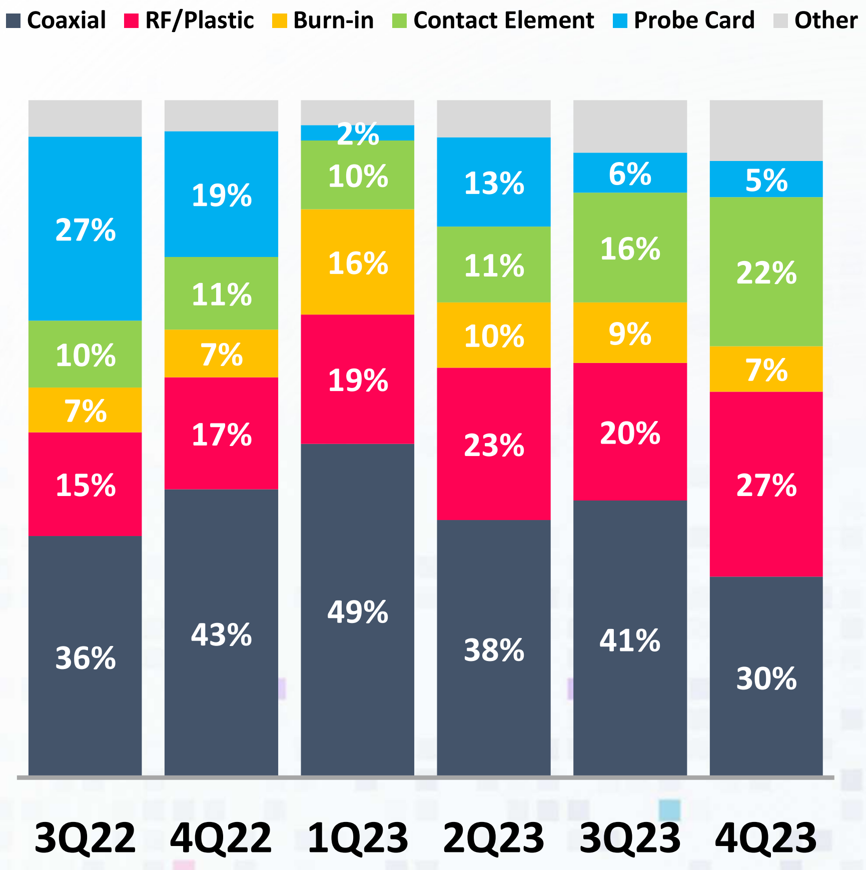
EPS (NT$)

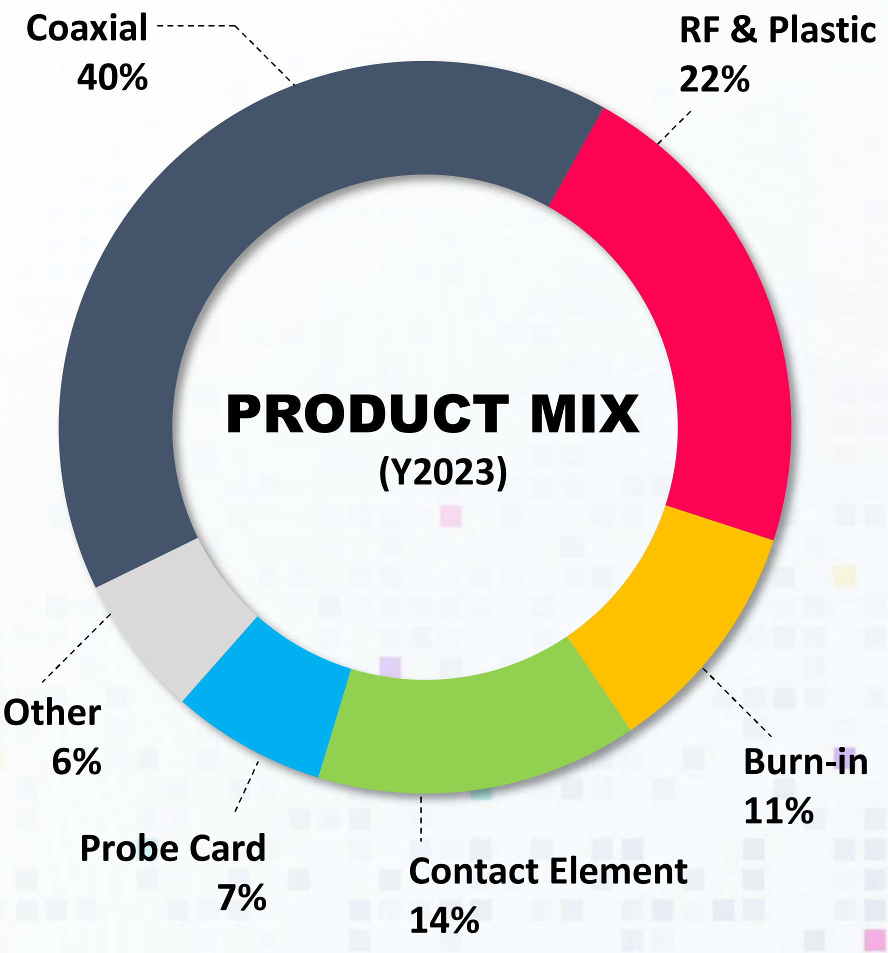
4.18	3.96	3.70	1.68

NET INCOME (NTD M)

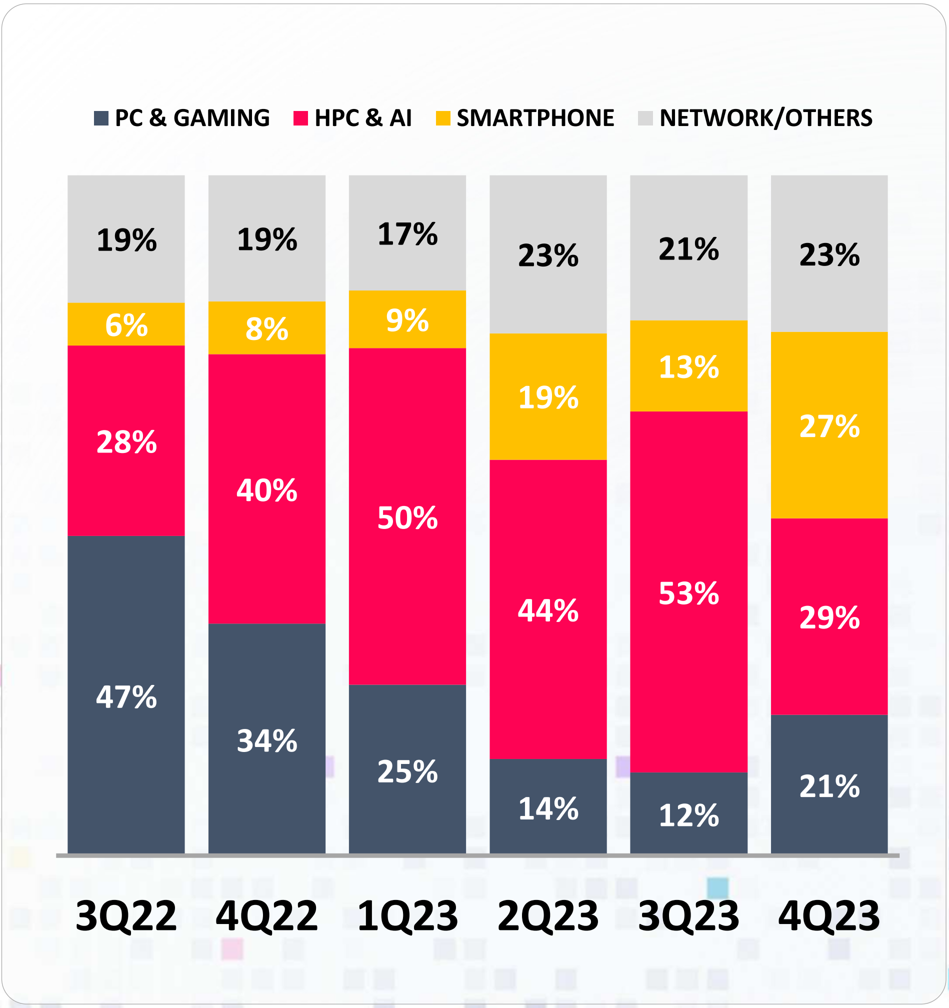


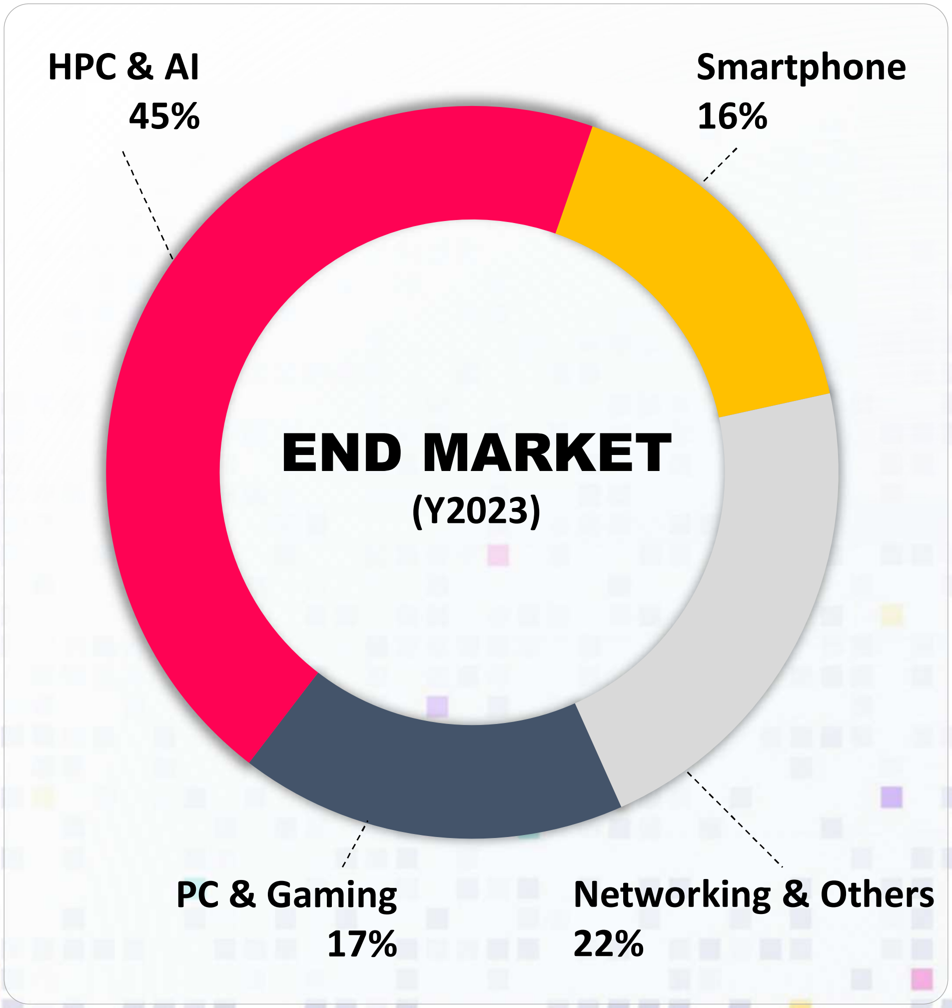
Revenue by Product Mix





Revenue by End Market





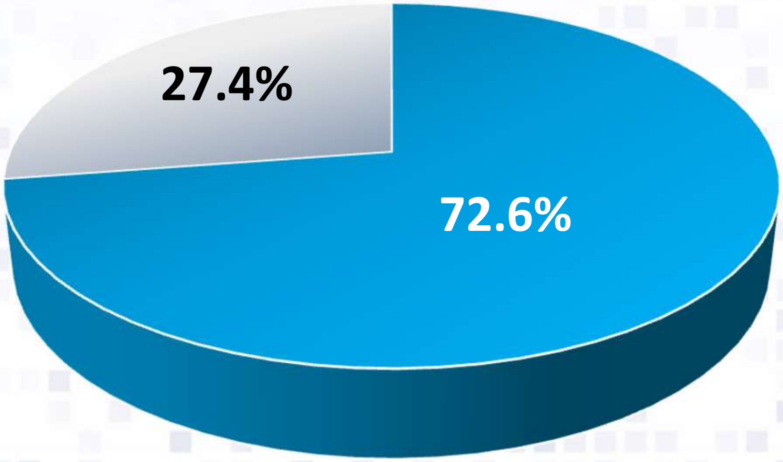
Driven by Advanced Technology

7nm (or equivalent node) and below

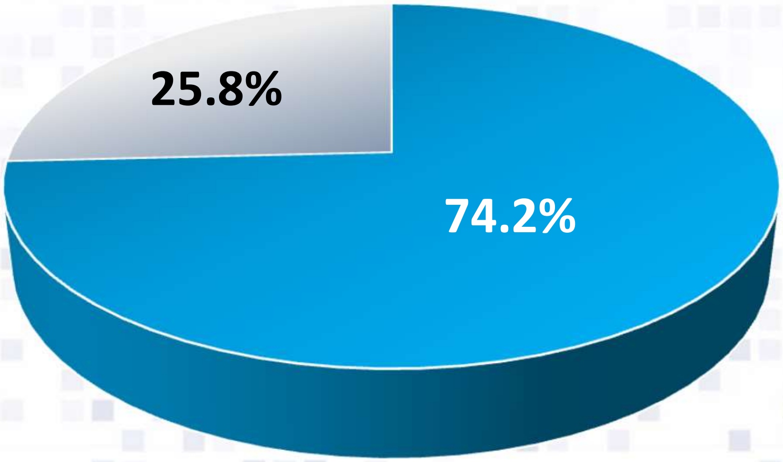
Mature Node

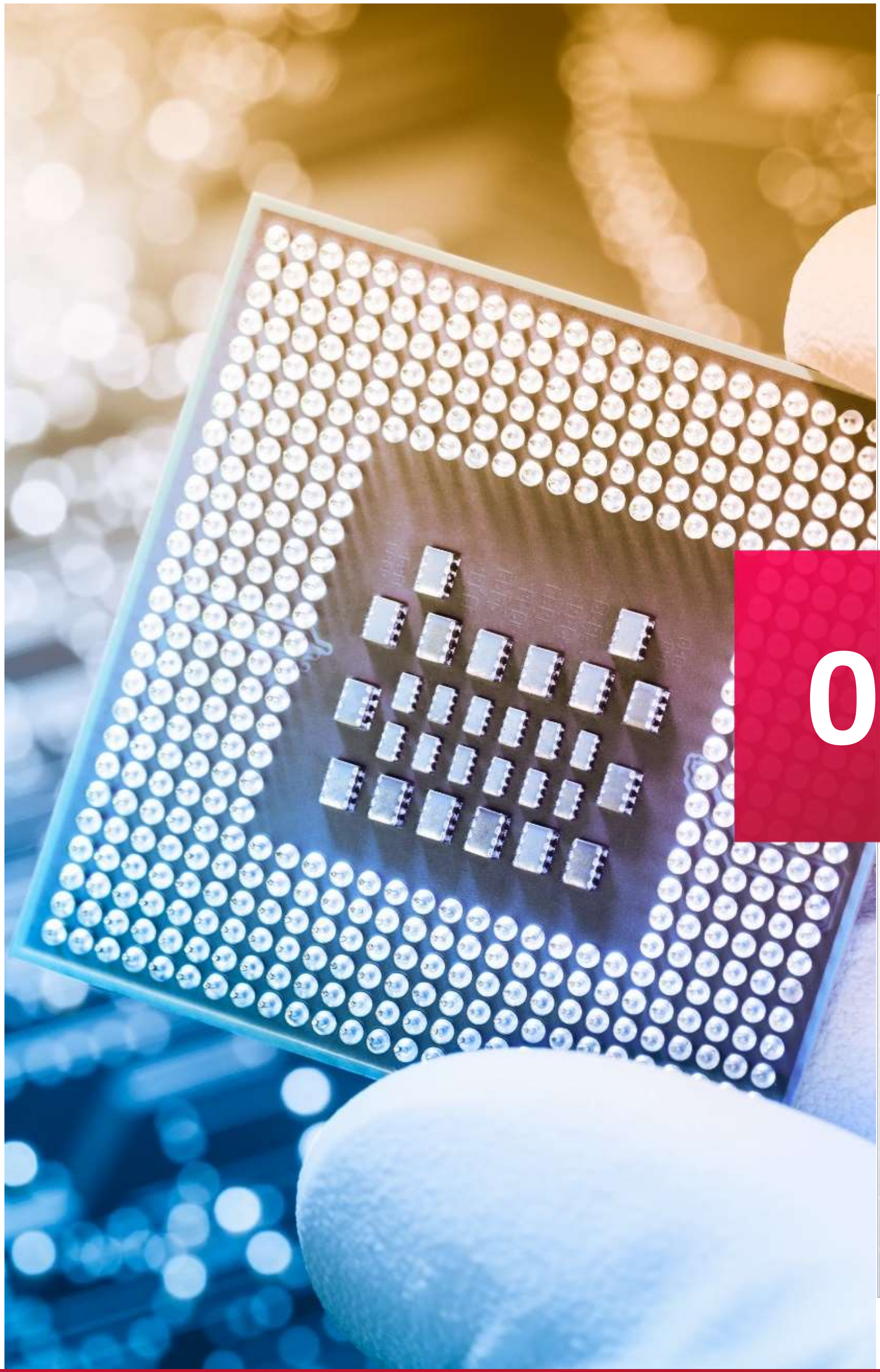
Advanced Node

2022



2023

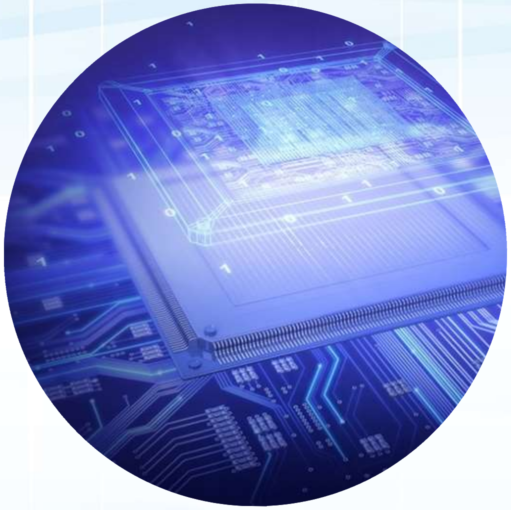




04

R&D Innovation

Driving Force for Future Innovation



HPC

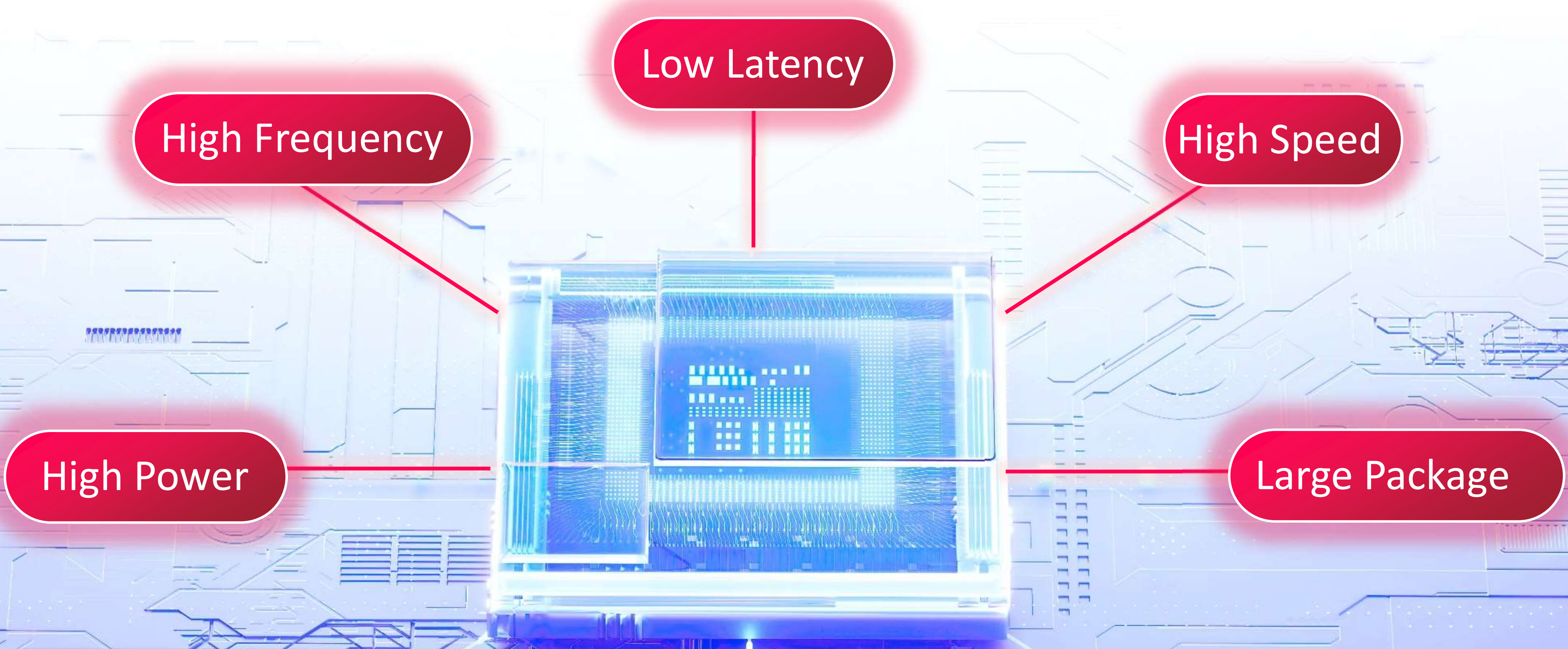
5G

AI

Gaming

Edge Computing

High-Performance Testing Driven by Advanced Packaging



Low Latency

High Frequency

High Speed

High Power

Large Package

Heterogeneous Integration

2.5D & 3D

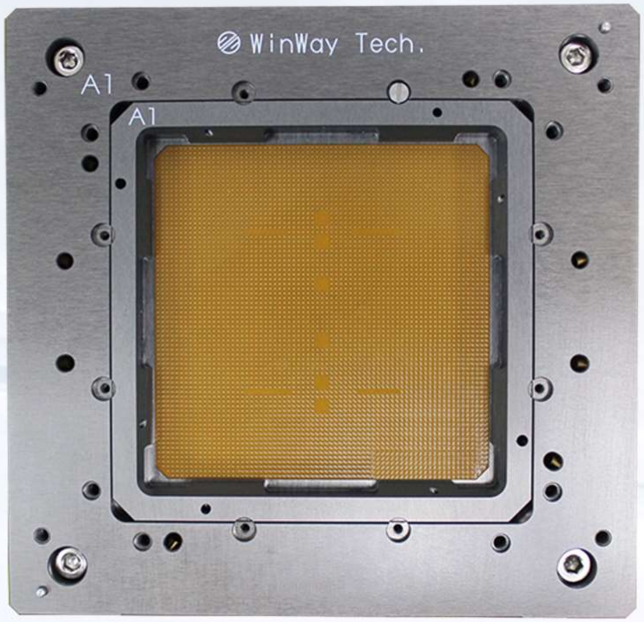
Chiplets

CoWoS

CPO

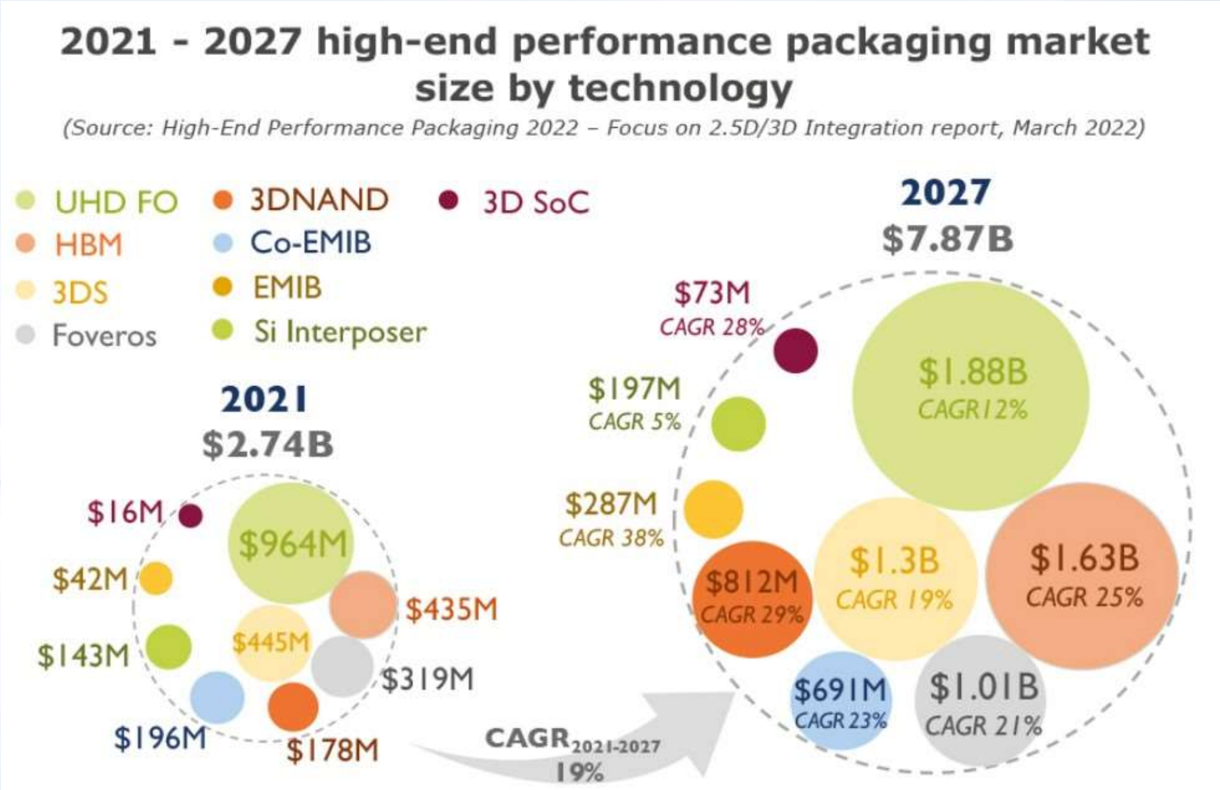
Introducing
WinWay HyperSocket™

Patented Product



Computing **Auto**

AI ASIC **VR**


2021 - 2027 high-end performance packaging market size by technology

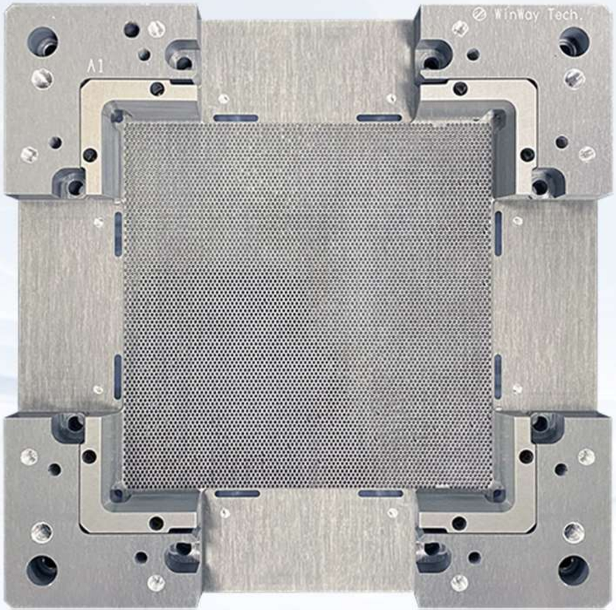
(Source: High-End Performance Packaging 2022 – Focus on 2.5D/3D Integration report, March 2022)

資料來源：Yole Group, 2023

Industry-Leading High Speed Test Socket

SerDes PAM4 224Gbps

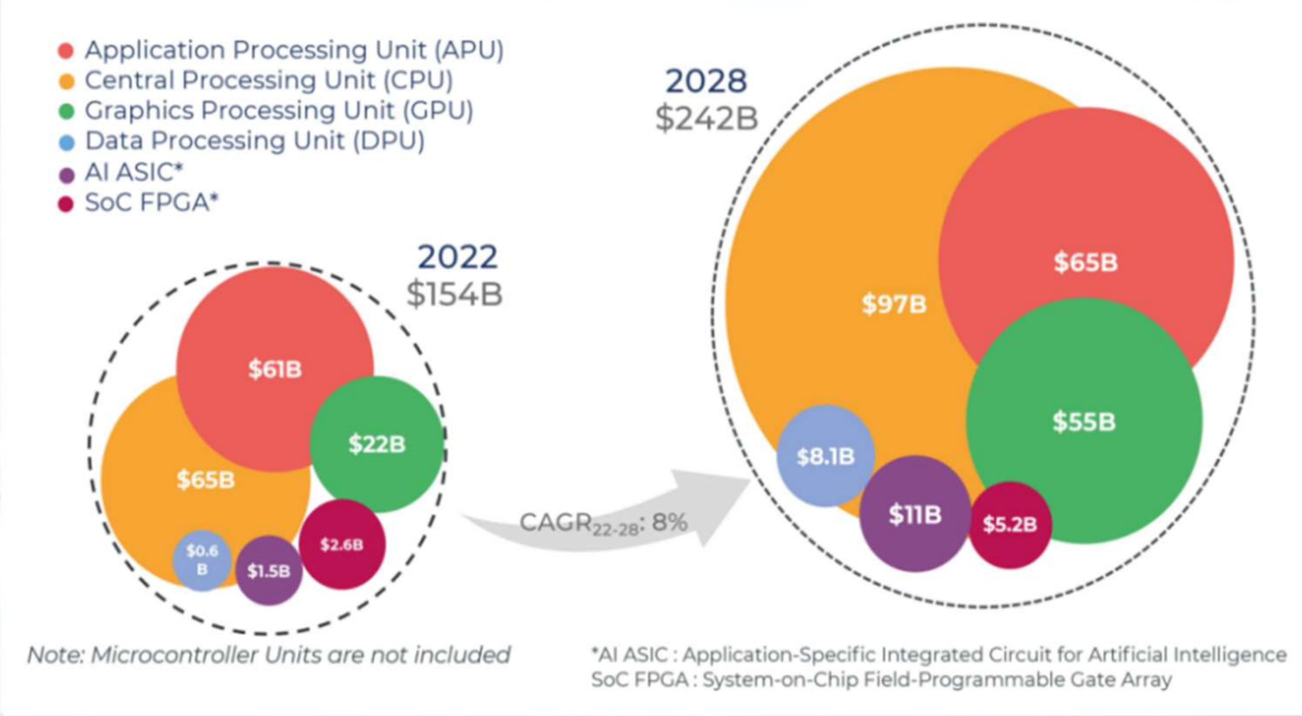
Patented Product



SerDes 224Gbps

PCIE Gen 7/GDDR7

All High-Speed Specifications



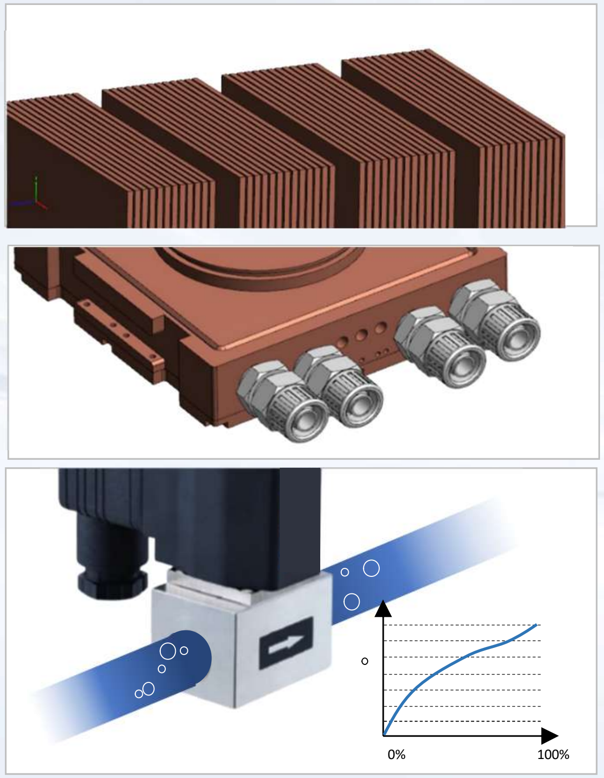
Note: Microcontroller Units are not included

*AI ASIC : Application-Specific Integrated Circuit for Artificial Intelligence
SoC FPGA : System-on-Chip Field-Programmable Gate Array

SOURCE : Yole Group, 2023

Leadership 2000W High Power Thermal
HEATCon Titan

Patented Product



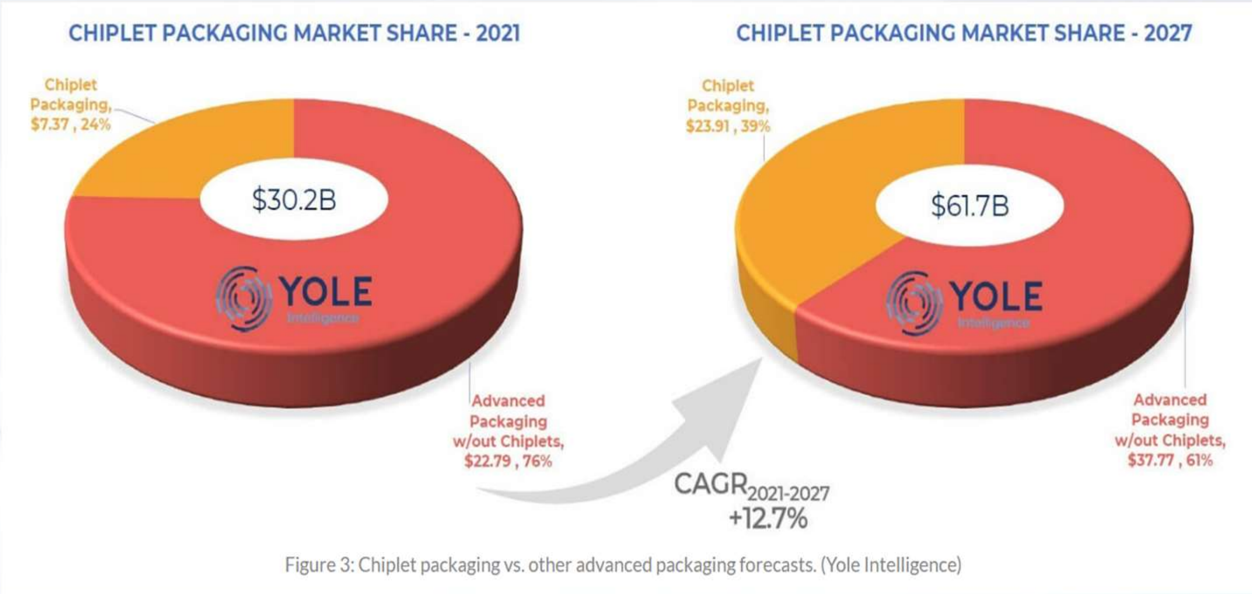


Figure 3: Chiplet packaging vs. other advanced packaging forecasts. (Yole Intelligence)

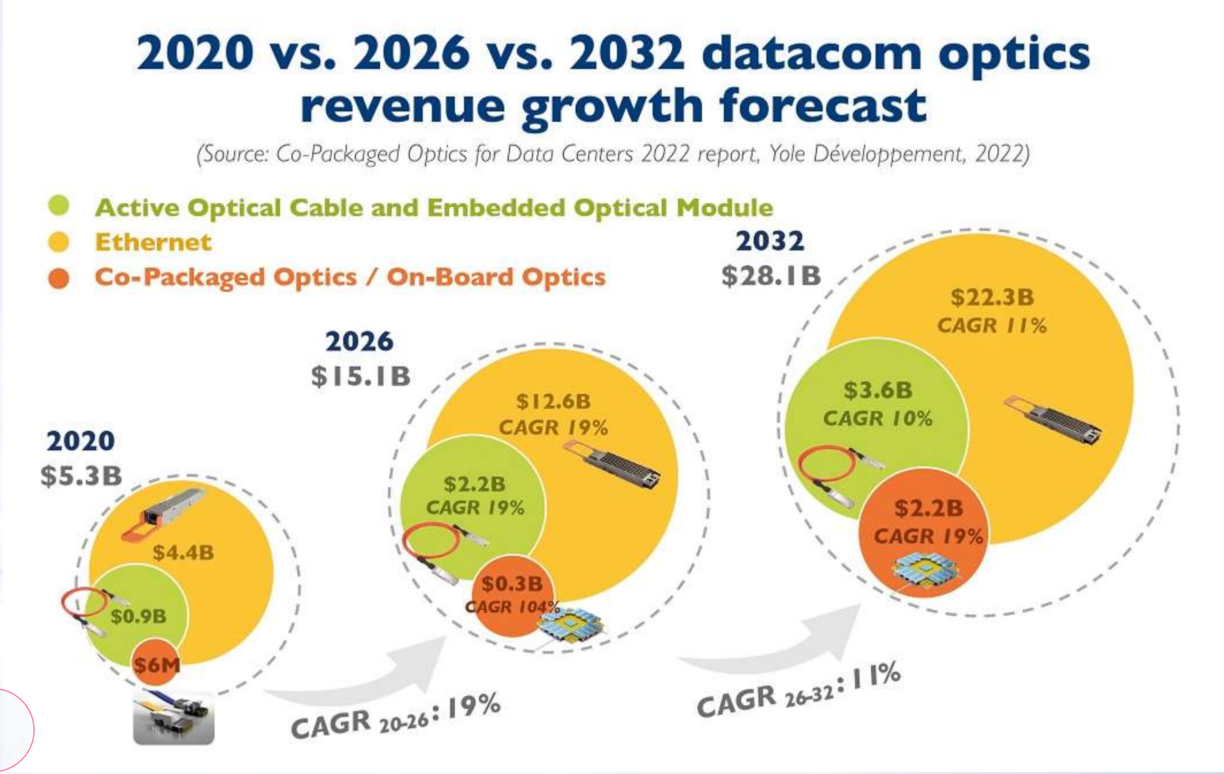
SOURCE：Yole Group, 2023

Chiplet/3D Package

Address Large Package Thermal Challenges

Enhanced thermal distribution across chip package

Introducing Integrated Wafer-Level Probing System for CPO



2020 vs. 2026 vs. 2032 datacom optics revenue growth forecast

(Source: Co-Packaged Optics for Data Centers 2022 report, Yole Développement, 2022)

Fine-pitch, double-sided probing system

Opto-electrical testing solution

CPO for future 800G/1.6T networks

SOURCE : Yole Group, 2023

Exclusive In-House Automation Equipment

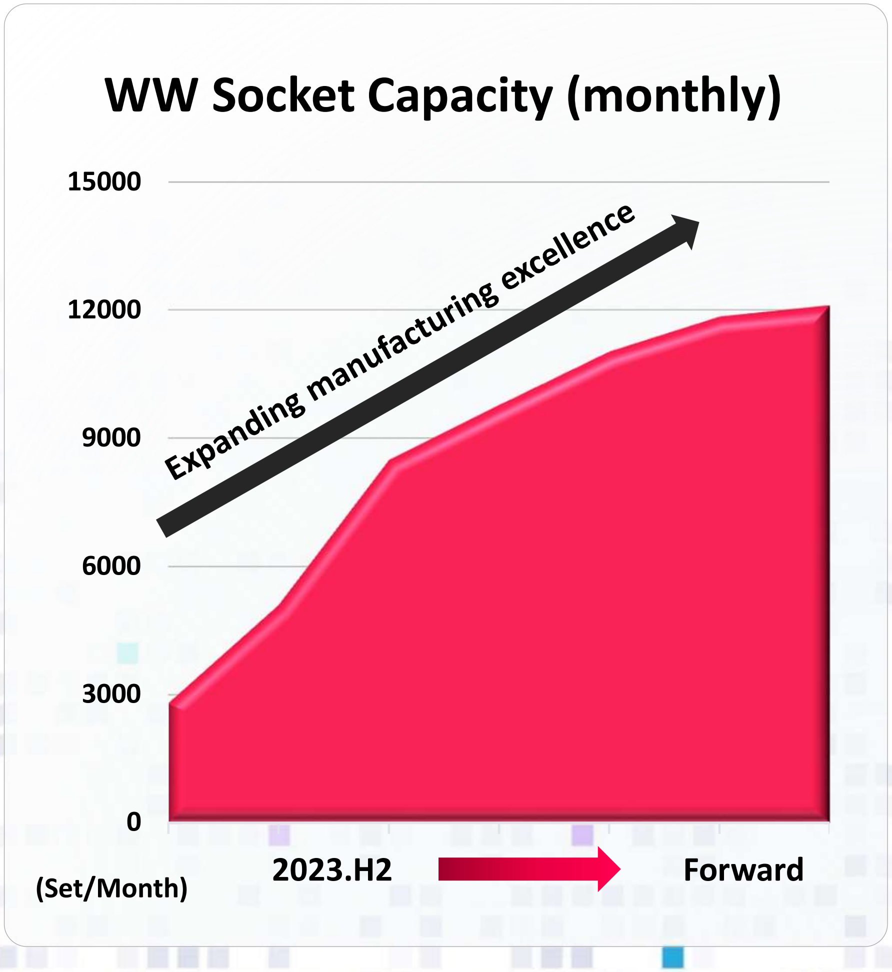
High-Speed Re-Pin System

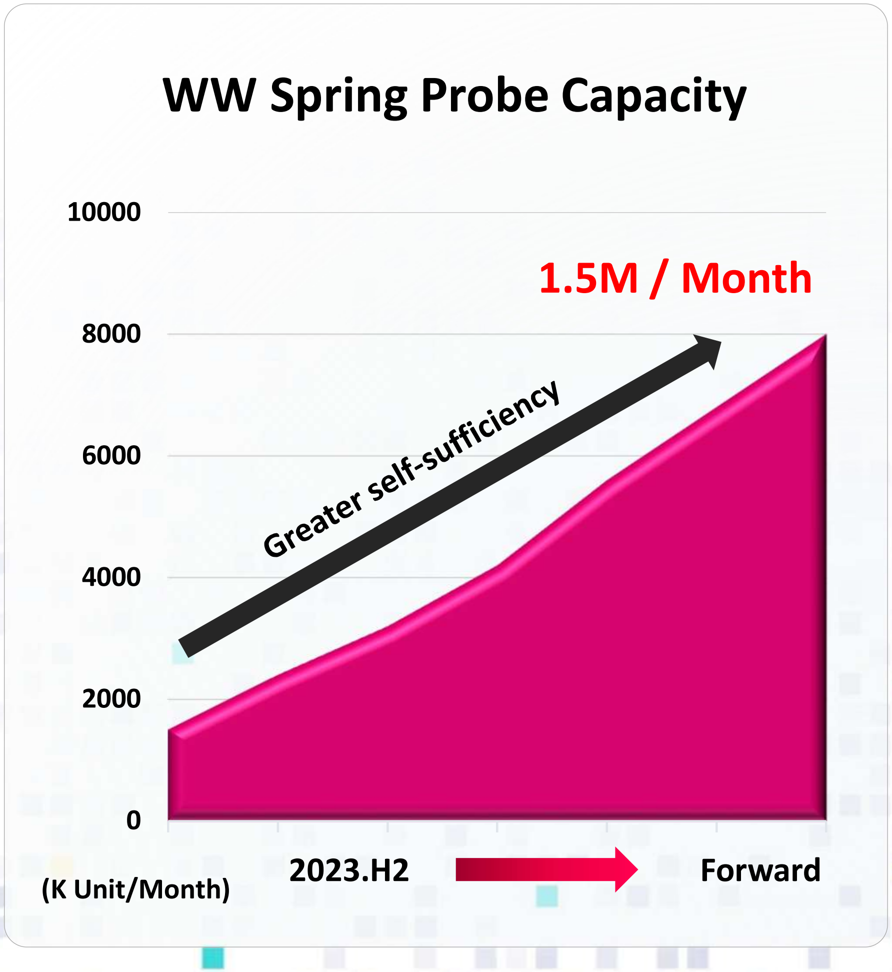
Patented Product

IC Design NPI

OSAT Production

Socket & Spring Probe All in House


WW Socket Capacity (monthly)


WW Spring Probe Capacity


Q
&
A

THANK YOU

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